

A4G150N1200MT4

1200V N-Channel MOSFET

Features

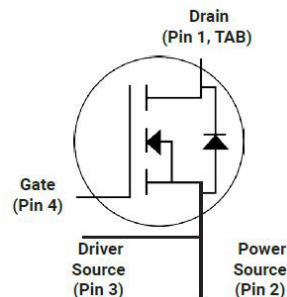
- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low $R_{DS(on)}$
- Easy to parallel and simple to drive
- ROHS Compliant, Halogen free
- 4th Generation SiC MOSFET Technology

Application

- EV motor drive
- High Voltage DC/DC Converters
- Switch Mode Power Supplies
- Solar inverters
- EV charging

Product Summary

V_{DS}	1200V
I_D	150A



Ordering Information

Part Number	Marking	Package	Packaging
A4G150N1200MT4	A4G150N1200MT4	TO-247-4L	Tube

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	1200	V
I_D	Drain Current (continuous) at $T_C=25^{\circ}\text{C}$	150	A
I_D	Drain Current (continuous) at $T_C=100^{\circ}\text{C}$	105	A
I_{DM}	Drain Current (pulsed)	330	A
V_{GS}	Gate-Source Voltage	-10/+22	V
P_D	Power Dissipation $T_C=25^{\circ}\text{C}$	625	W
T_J, T_{stg}	Junction and Storage Temperature Range	-55 to +175	$^{\circ}\text{C}$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Typical Performance-Static

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DS}	Drain-source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	1200			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=1200\text{V}, V_{GS}=0\text{V}, T_J=25^{\circ}\text{C}$			100	μA
I_{GSS}	Gate-body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=-10\text{ to }20\text{V}$			250	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=20\text{mA}$	2	2.8	4	V
$V_{GS(on)}$	Recommended turn-on Voltage	Static		15/18		V
$V_{GS(off)}$	Recommended turn-off Voltage			-5		V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS}=15\text{V}, I_D=75\text{A}$		12	15	m Ω
		$V_{GS}=15\text{V}, I_D=75\text{A}, T_J=175^{\circ}\text{C}$		20		
		$V_{GS}=18\text{V}, I_D=75\text{A}$		10	12.5	
		$V_{GS}=18\text{V}, I_D=75\text{A}, T_J=175^{\circ}\text{C}$		16.6		

A4G150N1200MT4

Typical Performance-Dynamic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
C _{iss}	Input Capacitance	V _{DS} =1000V, f=1MHz V _{AC} =25mV		7980		pF
C _{oss}	Output Capacitance			312		pF
C _{rss}	Reverse Transfer Capacitance			16		pF
g _{fs}	Transconductance	V _{DS} =20V, I _D =50A		52		S
E _{OSS}	C _{oss} Stored Energy	V _{DS} =1000V, f=1MHz		173		uJ
E _{ON}	Turn-On Energy (Body Diode)	V _{DS} =800V V _{GS} =-5/18V, I _D =75A L=68uH, T _J =175°C		1.28		mJ
E _{OFF}	Turn-Off Energy (Body Diode)			1.02		mJ
Q _g	Total Gate Charge			298		nC
Q _{gs}	Gate-source Charge	V _{GS} =-5/18V		82		nC
Q _{gd}	Gate-Drain Charge	I _D =75A		98		nC
R _{G(int)}	Internal Gate Resistance	f=1MHz, V _{AC} =25mV		2.0		Ω
t _{d(on)}	Turn-on Delay Time	V _{DS} =800V V _{GS} =-5/18V, I _D =75A L=68uH, R _{ext} =2.5Ω		36		ns
t _r	Rise Time			29		ns
t _{d(off)}	Turn-off Delay Time			80		ns
t _f	Fall Time			19		ns

Typical Performance-Reverse Diode (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{FSD}	Forward Voltage	V _{GS} =0V, I _F =55A, T _J =25°C		3.1	6	V
		V _{GS} =0V, I _F =55A, T _J =175°C		3.3	6	V
I _S	Continuous Diode Forward Current	V _{GS} =0V, T _C =25°C		120		A
t _{rr}	Reverse Recovery Time	V _{GS} =-5V, I _F =75A V _R =800V di/dt=1300A/μs, T _J =175°C		120		ns
Q _{rr}	Reverse Recovery Charge			797		nC
I _{rrm}	Peak Reverse Recovery Current			22		A

Thermal Characteristics

Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	0.24	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	40	°C/W

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of T_J(max)=175°C.

A4G150N1200MT4

Electrical Characteristics

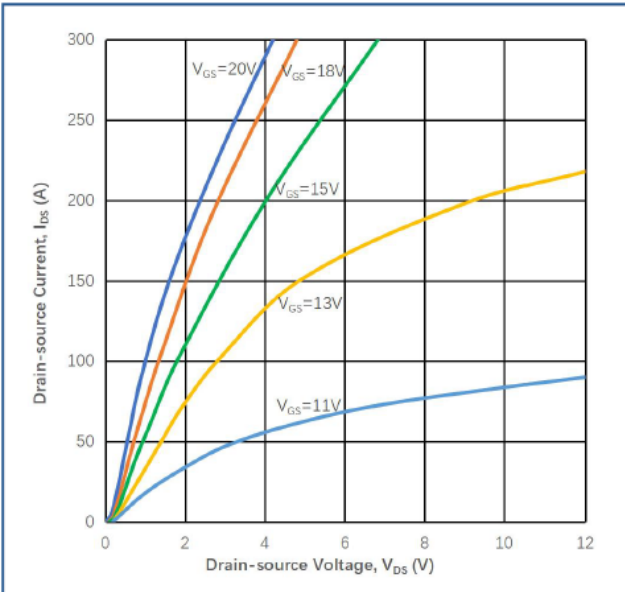


Figure 1

Output Characteristics ($T_J = 25^\circ\text{C}$)

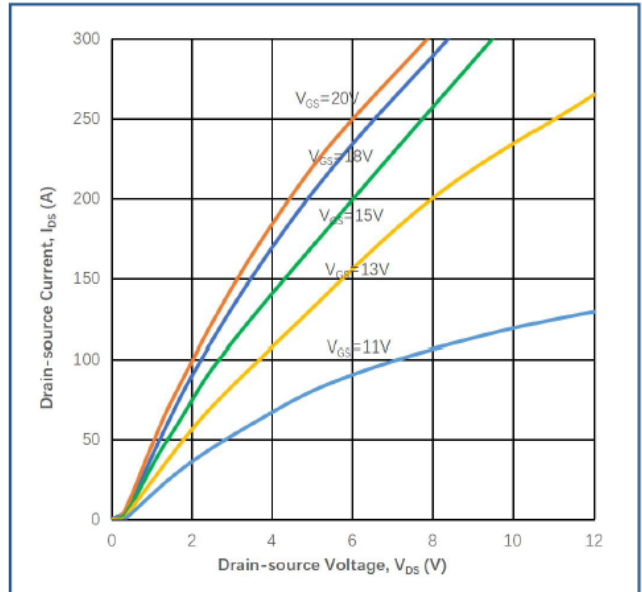


Figure 2

Output Characteristics ($T_J = 175^\circ\text{C}$)

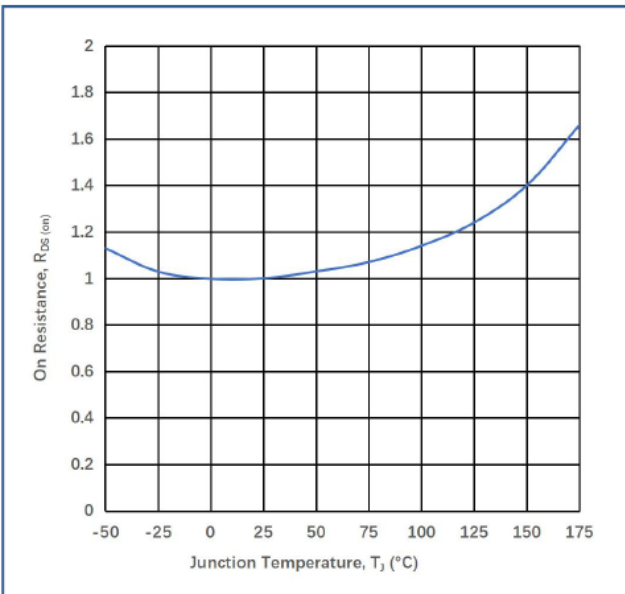


Figure 3

Normalized On-resistance vs. Temperature

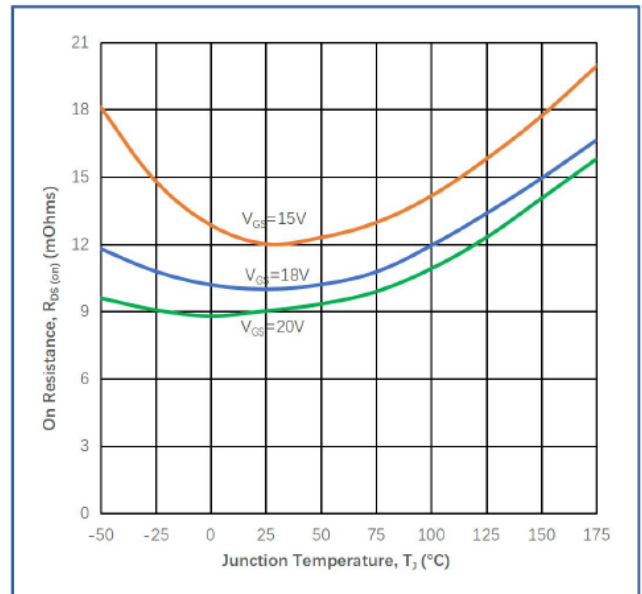


Figure 4

On-resistance vs. Temperature

A4G150N1200MT4

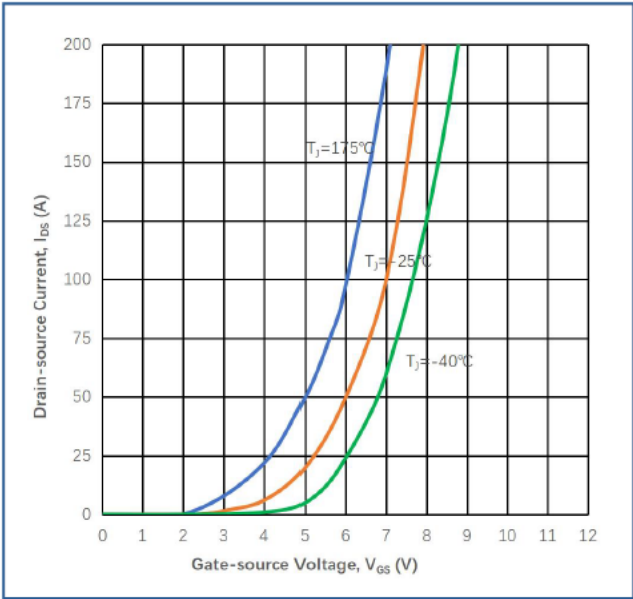


Figure 5
Transfer Characteristic

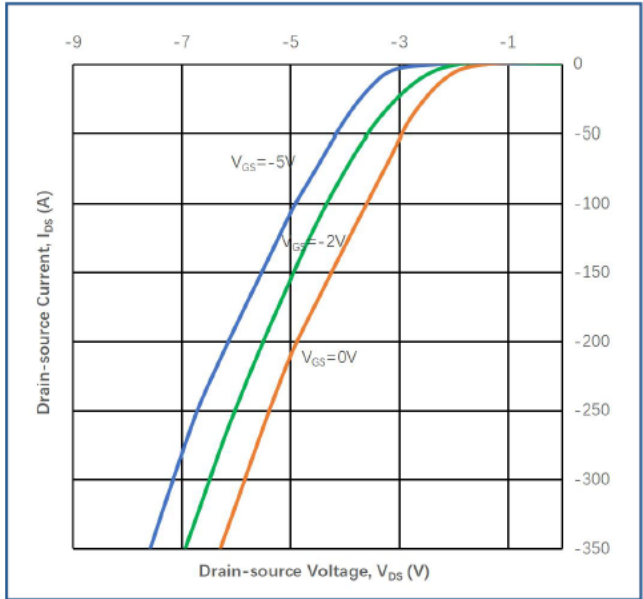


Figure 6
Body Diode Characteristic at 25°C

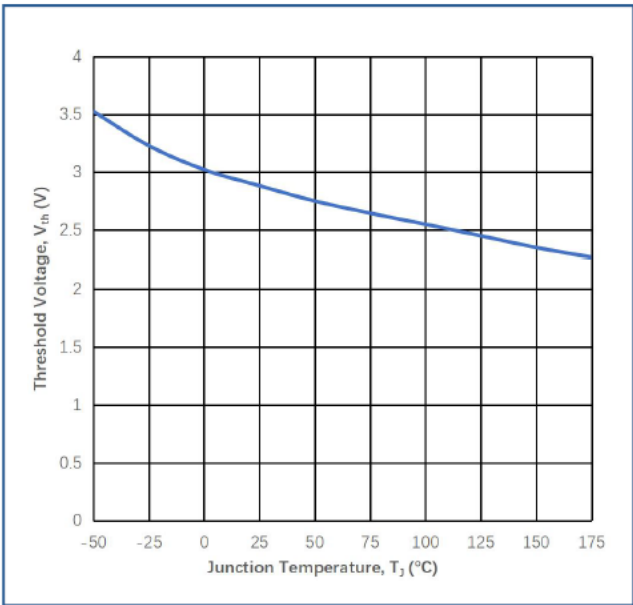


Figure 7
Threshold Voltage vs. Temperature

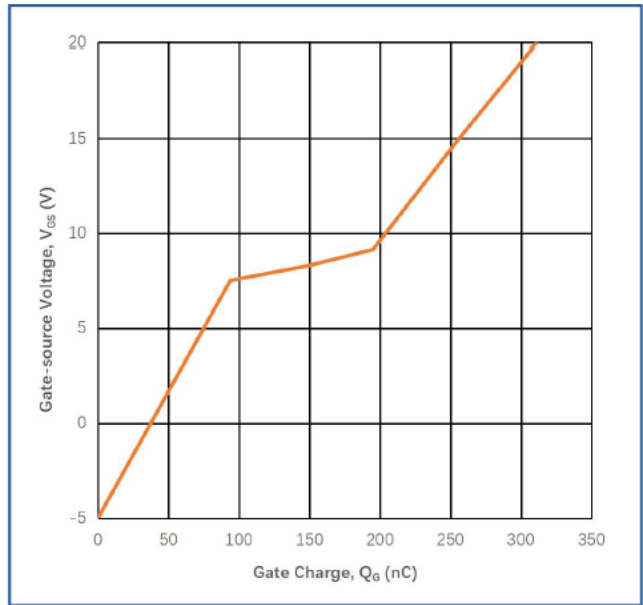


Figure 8
Gate Charge Characteristics

A4G150N1200MT4

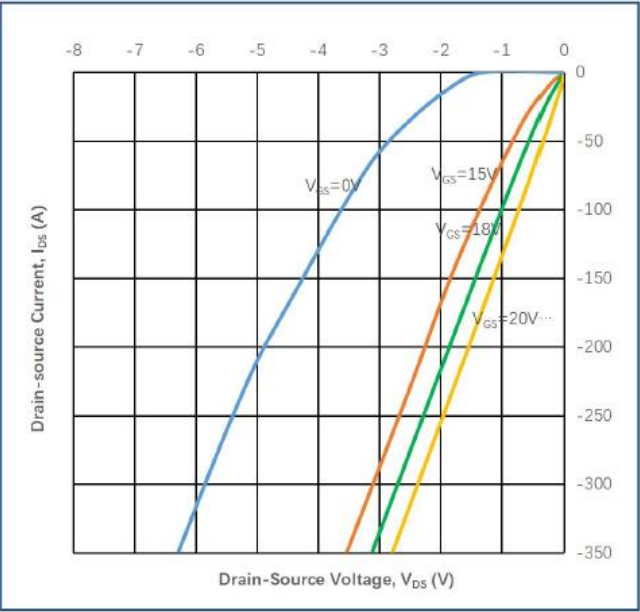


Figure 9

3rd Quadrant Characteristic at 25°C

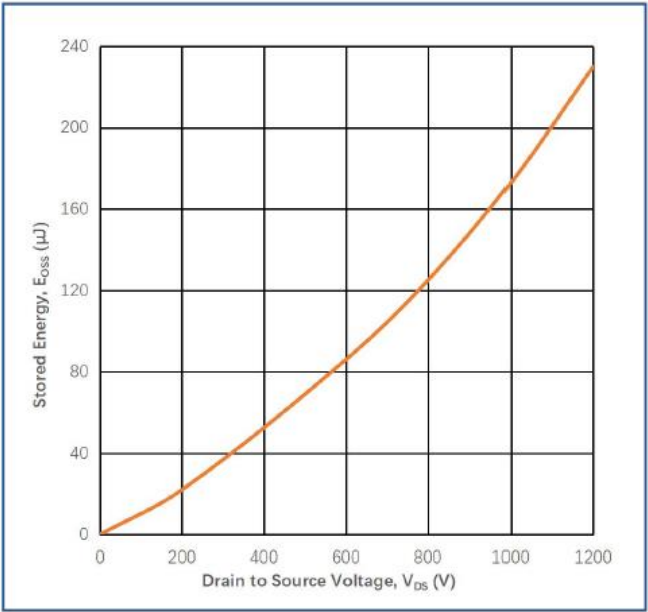


Figure 10

Output Capacitor Stored Energy

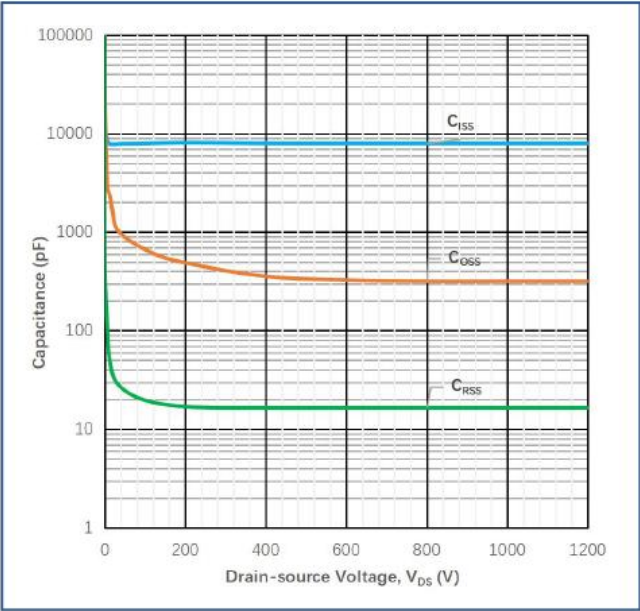


Figure 11

Capacitances vs. Drain-source

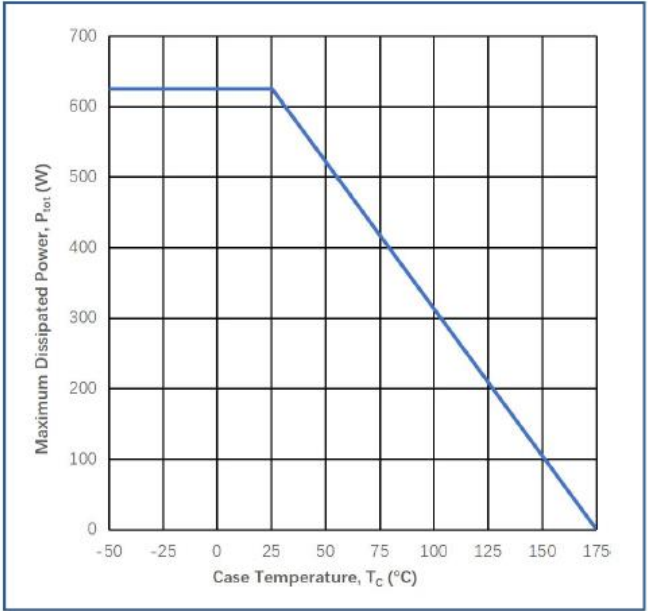


Figure 12

Max Power Dissipation Derating vs T_C

A4G150N1200MT4

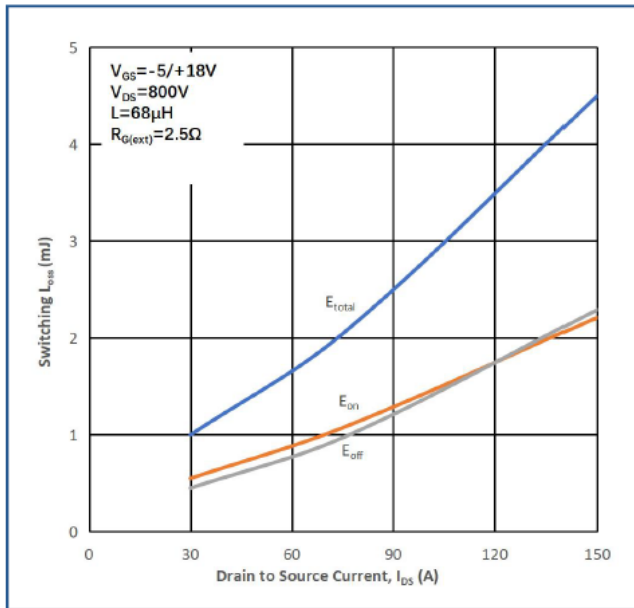


Figure 13

Switching Energy vs. Drain Current

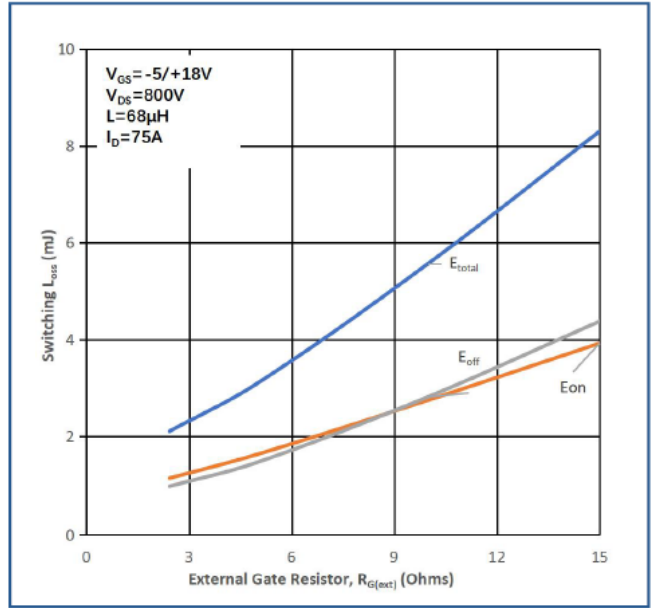


Figure 14

Switching Energy vs. $R_{G(ext)}$

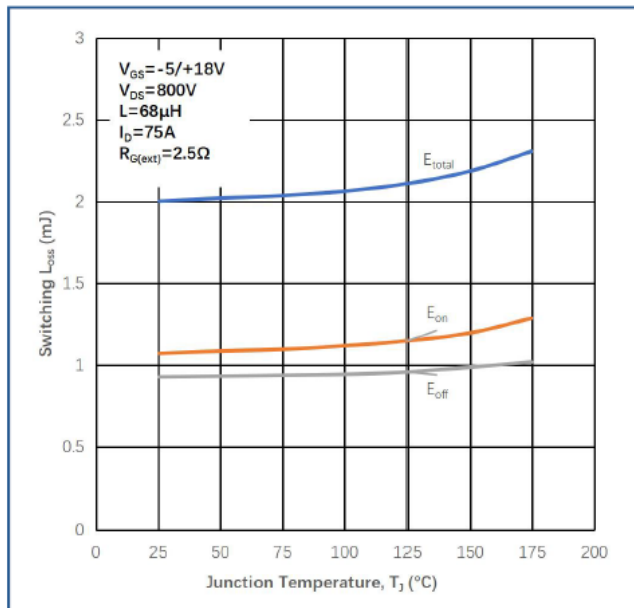


Figure 15

Switching Energy vs. Temperature

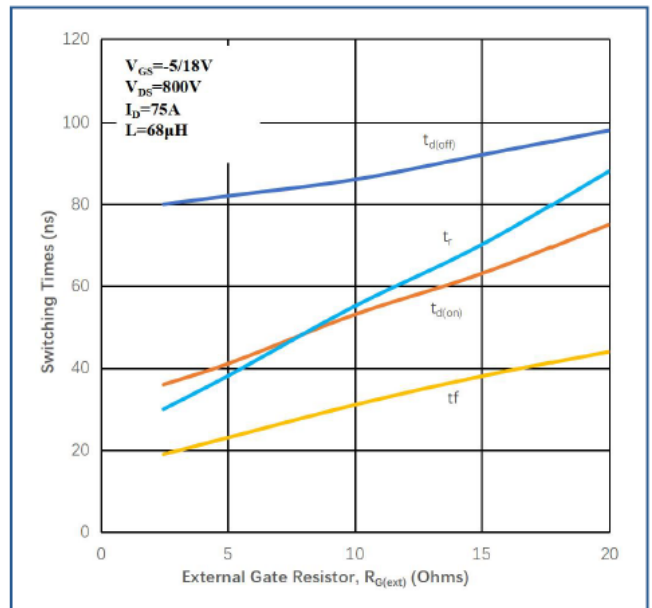


Figure 16

Switching Times vs. $R_{G(ext)}$

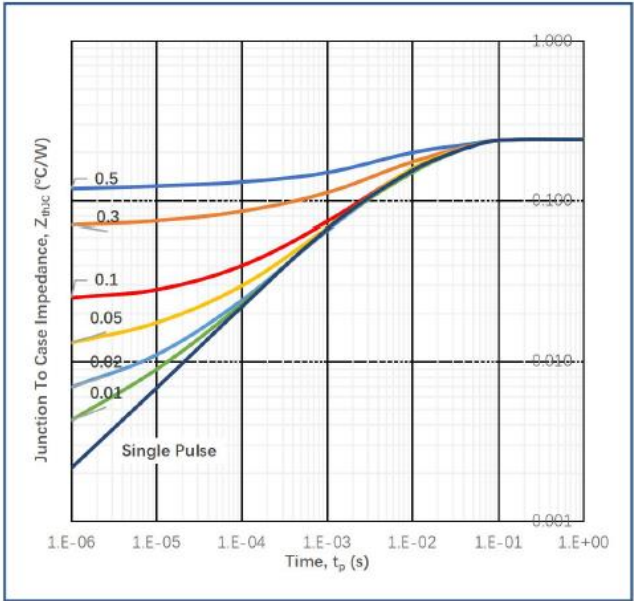


Figure 17

Transient Thermal Impedance

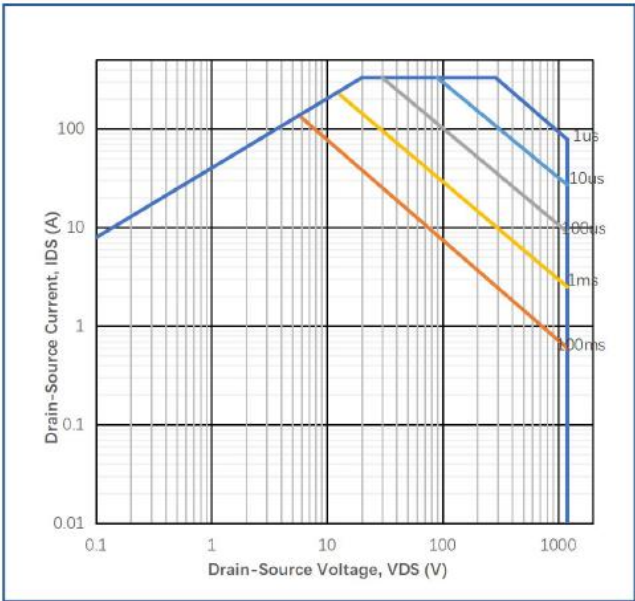
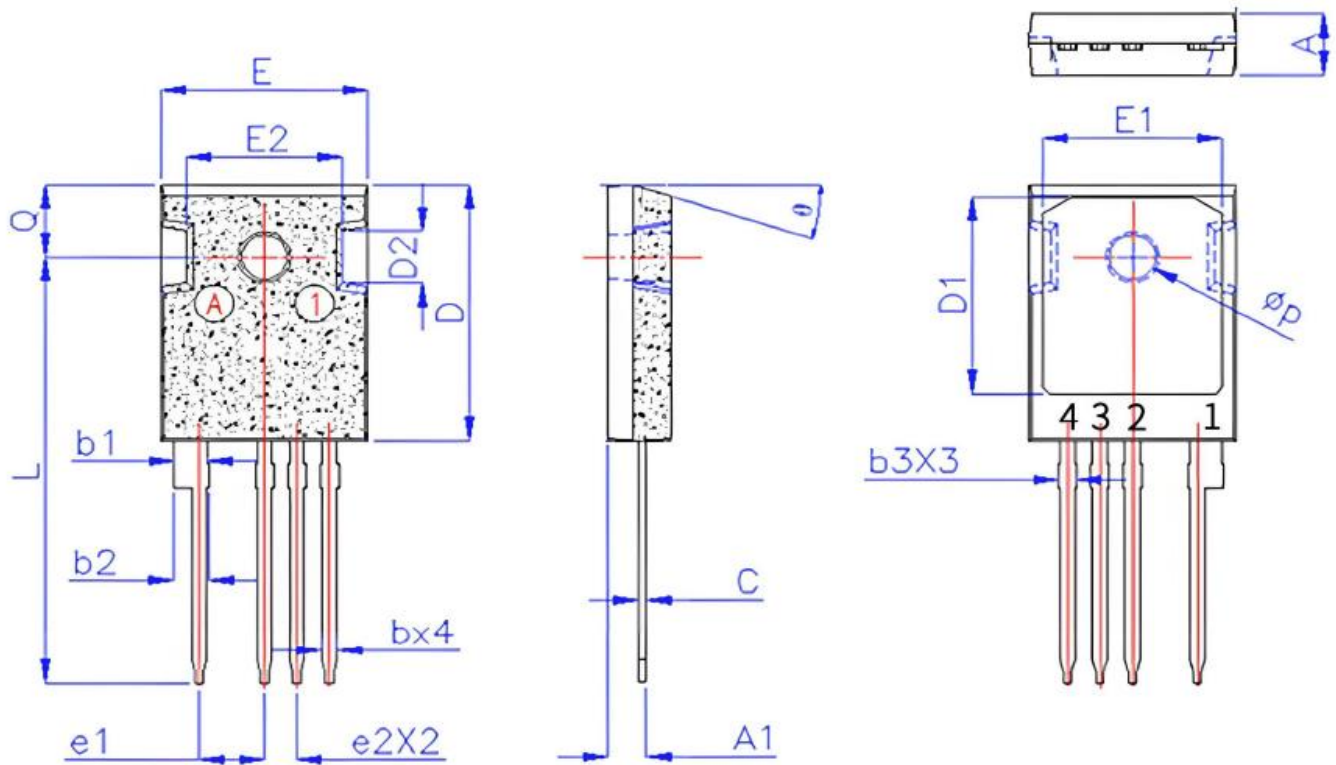


Figure 18

Safe Operating Area

A4G150N1200MT4

Package Drawing TO-247-4L



Dimensions

Symbols	Dimensions in millimeters			Dimensions in inches		
	Min.	Type	Max.	Min.	Type	Max.
A	4.80	5.00	5.20	0.189	0.197	0.205
A1	2.85	3.00	3.15	0.112	0.118	0.124
b	1.15	1.20	1.25	0.045	0.047	0.049
b1	2.40	2.50	2.10	0.094	0.098	0.102
b2	2.61	2.76	3.10	0.103	0.109	0.155
b3	1.30	1.42	1.57	0.051	0.056	0.062
C	0.55	0.60	0.65	0.022	0.024	0.026
D	20.80	21.00	21.20	0.819	0.827	0.835
D1	15.94	16.24	16.54	0.628	0.639	0.651
D2	4.30 BSC			0.169 BSC		
e1	4.93	5.08	5.23	0.194	0.200	0.206
e2	2.39	2.54	2.69	0.094	0.100	0.106
E	15.95	16.15	16.35	0.628	0.636	0.644
E1	13.82	14.02	14.26	0.544	0.552	0.561
E2	12.00	12.20	12.40	0.472	0.480	0.488
L	34.65	35.05	35.45	1.364	1.380	1.396
Q	5.85	5.95	6.05	0.230	0.234	0.238
øP	3.45	3.60	3.75	0.136	0.142	0.148
θ	17.5°			0.689°		

A4G150N1200MT4

Revision version	Description	Date
1	Initial	04.2025